BAV756DW

QUAD SURFACE MOUNT SWITCHING DIODE ARRAY

Please click here to visit our online spice models database.

Features

- Fast Switching Speed
- Ultra-Small Surface Mount Package
- For General Purpose Switching Applications
- High Conductance
- One BAV70 Circuit and One BAW56 Circuit In One Package
- Easily Connected As Full Wave Bridge
- **Lead Free/RoHS Compliant (Note 3)**
- **"Green" Device (Notes 4 and 5)**

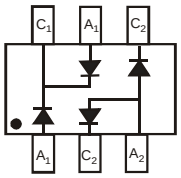
Mechanical Data

- Case: SOT-363
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals: Solderable per MIL-STD-202, Method 208
- Lead Free Plating (Matte Tin Finish annealed over Alloy 42 leadframe).
- Polarity: See Diagram
- Marking Information: See Page 2
- Ordering Information: See Page 2
- Weight: 0.006 grams (approximate)

SOT-363



TOP VIEW



TOP VIEW
Internal Schematic

Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage	V_{RM}	100	V
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	75	V
RMS Reverse Voltage	$V_{R(RMS)}$	53	V
Forward Continuous Current (Notes 1 and 2)	I_{FM}	300	mA
Average Rectified Output Current (Notes 1 and 2)	I_O	150	mA
Non-Repetitive Peak Forward Surge Current @ t = 1.0μs @ t = 1.0s	I_{FSM}	2.0 1.0	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Notes 1 and 2)	P_D	200	mW
Power Dissipation T_S = 60°C (Note 2)	P_D	300	mW
Thermal Resistance Junction to Ambient Air (Notes 1 and 2)	$R_{\theta JA}$	625	°C/W
Thermal Resistance Junction to Soldering Point (Note 2)	$R_{\theta JS}$	275	°C/W
Operating and Storage Temperature Range	T_J, T_{STG}	-65 to +150	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	$V_{(BR)R}$	75	—	V	I_R = 2.5μA
Forward Voltage	V_F	—	0.715 0.855 1.0 1.25	V	I_F = 1.0mA I_F = 10mA I_F = 50mA I_F = 150mA
Reverse Current (Note 6)	I_R	—	2.5 50 30 25	μA μA μA nA	V_R = 75V V_R = 75V, T_J = 150°C V_R = 25V, T_J = 150°C V_R = 20V
Total Capacitance	C_T	—	2.0	pF	V_R = 0, f = 1.0MHz
Reverse Recovery Time	t_{rr}	—	4.0	ns	I_F = I_R = 10mA, I_{rr} = 0.1 x I_R, R_L = 100Ω

Notes:
1. Device mounted on FR-4 PC board with recommended pad layout, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.
2. One or more diodes loaded.
3. No purposefully added lead.
4. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
5. Product manufactured with Date Code UO (week 40, 2007) and newer are built with Green Molding Compound. Product manufactured prior to Date Code UO are built with Non-Green Molding Compound and may contain Halogens or Sb_2O_3 Fire Retardants.
6. Short duration pulse test used to minimize self-heating effect.

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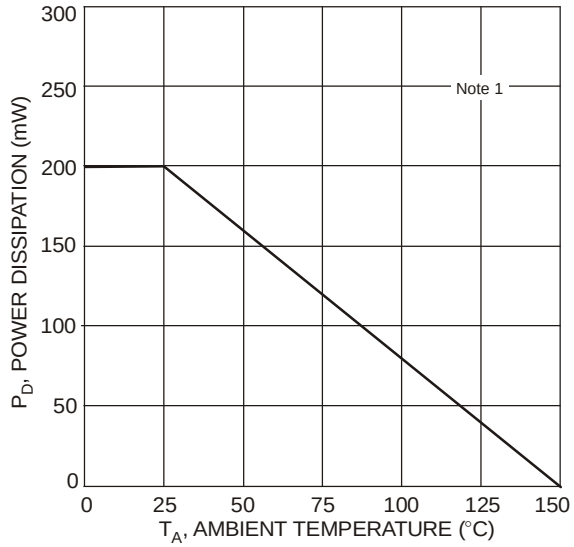


Fig. 1 Power Derating Curve, Total Package

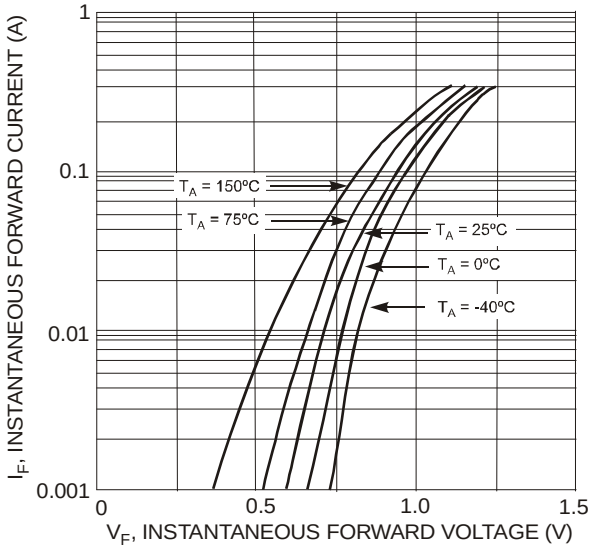


Fig. 2 Typical Forward Characteristics, Per Element

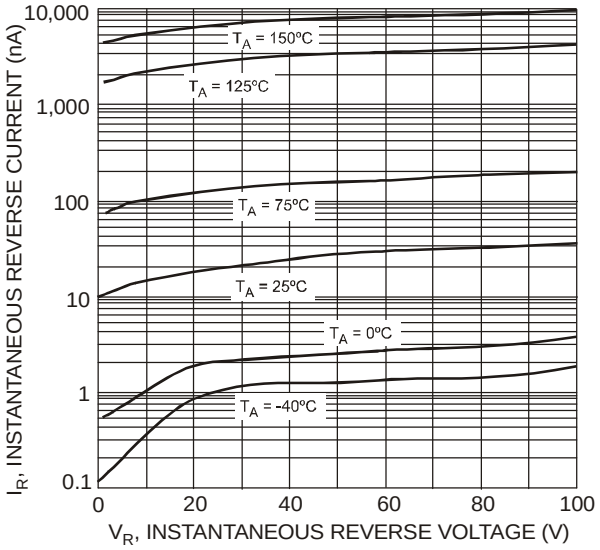


Fig. 3 Typical Reverse Characteristics, Per Element

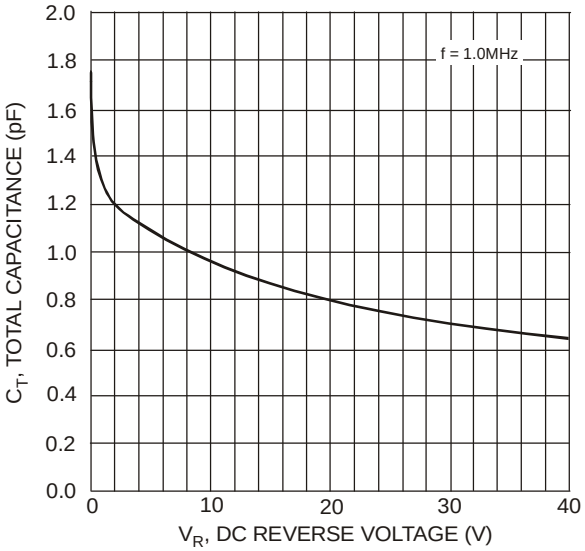


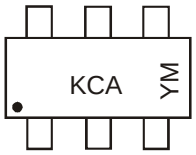
Fig. 4 Total Capacitance vs. Reverse Voltage, Per Element

Ordering Information (Notes 5 & 7)

Part Number	Case	Packaging
BAV756DW-7-F	SOT-363	3000/Tape & Reel

Notes: 7. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information



KCA = Product Type Marking Code
YM = Date Code Marking
Y = Year ex: N = 2002
M = Month ex: 9 = September

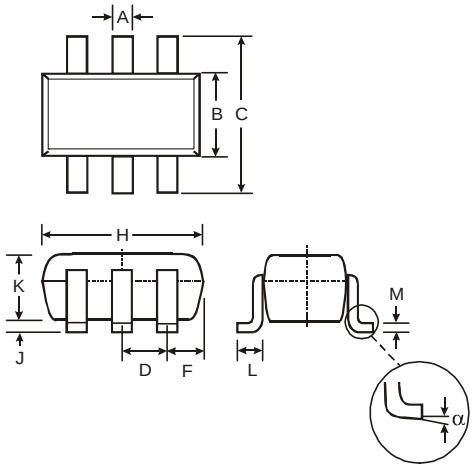
Date Code Key

Year	2001	2002	2003	2004	2005	2006	2007	2008	2009	2010	2111	2012
Code	M	N	P	R	S	T	U	V	W	X	Y	Z

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

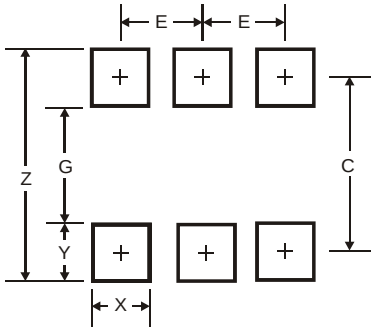
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Package Outline Dimensions



SOT-363		
Dim	**Min**	**Max**
A	0.10	0.30
B	1.15	1.35
C	2.00	2.20
D	0.65 Nominal	
F	0.30	0.40
H	1.80	2.20
J	—	0.10
K	0.90	1.00
L	0.25	0.40
M	0.10	0.25
α	0°	8°
All Dimensions in mm		

Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.5
G	1.3
X	0.42
Y	0.6
C	1.9
E	0.65

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